

(51) Int Cl.⁶: **H01L 23/532**

(22) Date of filing: 16.12.1997

(72) Inventors:

- Jln, Changming
Dallas, Texas 75243 (US)
- Yamanaka, Stacey
Dallas, Texas 75240 (US)
- List, R Scott
Dallas, Texas 75229 (US)

(71) Applicant: **TEXAS INSTRUMENTS
INCORPORATED**
Dallas Texas 75265 (US)

(74) Representative: **Darby, David Thomas et al**
Abel & Imray
Northumberland House
303-306 High Holborn
London WC1V 7LH (GB)

(54) Improvements in or relating to integrated circuits

(57) An integrated circuit with an intermetal level dielectric (IMD) including an organic-silica hybrid (110) and located between metal lines (104).

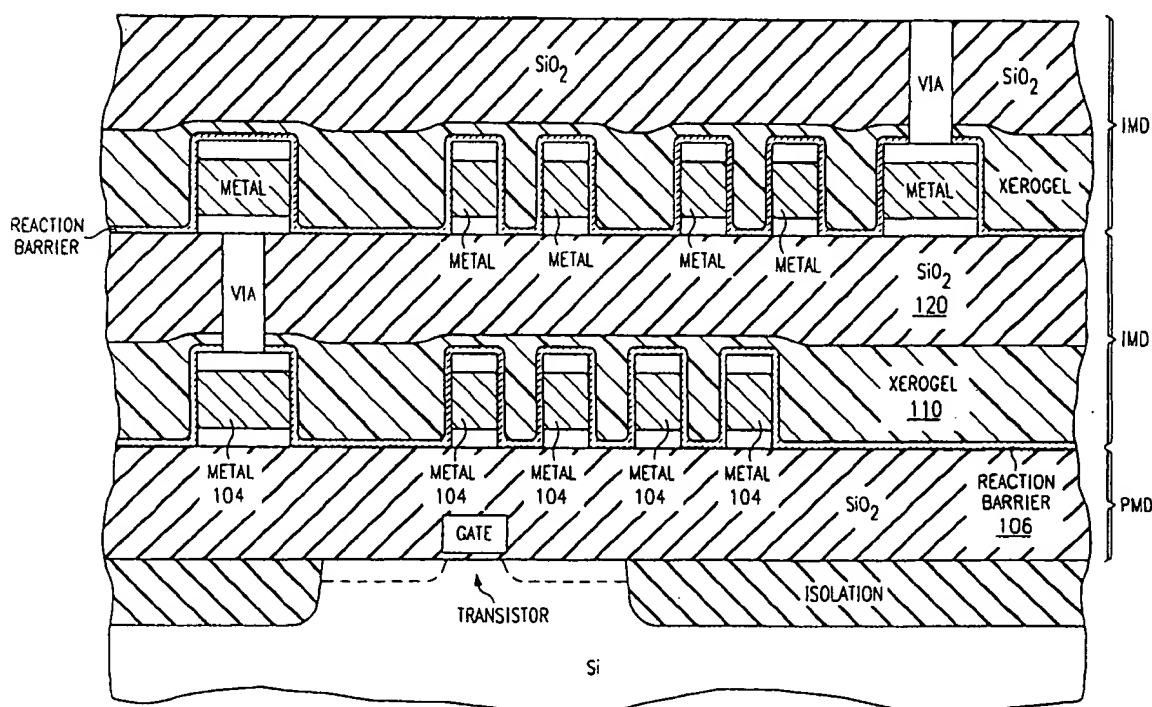


Figure 3.

Description

FIELD OF THE INVENTION

The invention relates generally to integrated circuits and, more particularly, to integrated circuit insulation materials and fabrication methods.

BACKGROUND OF THE INVENTION

The performance of high density integrated circuits is dominated by metal interconnect level RC delays due to the resistivity of the metal lines and the capacitive coupling between adjacent lines. The capacitive coupling can be reduced by decreasing the relative permittivity (dielectric constant) of the dielectric (insulator) between adjacent lines.

Various dielectric materials have been suggested for use in silicon integrated circuits; namely, silicon dioxide (currently the dominant dielectric material with a relative permittivity about 4.0), inorganic materials such as fluorinated silicon dioxide (relative permittivities about 3.0-4.0), organic materials such as polyimide, parylene, amorphous ptfе (relative permittivities about 1.9-3.9), and porous dielectrics such as silicon dioxide xerogels (relative permittivity depending upon pore size and density, typically 1.3-3.0). Indeed, the pore sizes in silica xerogels are usually much smaller than the integrated circuit feature size; see Smith et al, Preparation of Low-Density Xerogel at Ambient Pressure for Low k Dielectrics, 381 Mat.Res.Soc. Symp.Proc. 261 (1995). The porosity can be up to 99%.

Thin film silica xerogels for integrated circuit dielectrics can be fabricated by the generic steps of precursor preparation, spin coating, aging, solvent exchange, and drying.

An alkoxide is hydrolyzed in a solvent as shown by the reaction illustrated in Figure 1.

The solvent conveniently could be aqueous ethanol, for example.

Figure 2 illustrates the condensation of the hydrolyzed alkoxide.

The condensation can be controlled so that spin coating occurs after partial condensation to an appropriate viscosity.

The solvent exchange step replaces the original solvent residing within the pores of the condensed network by low-surface-tension solvent to reduce the capillary pressure during drying and to minimize the collapse of pores. United States Patent No.5,561,318 discloses variations of the process.

However, porous silica has not yet become manufacturable. Shea et al, Arylsilsesquioxane Gels and related Materials, New Hybrids of Organic and Inorganic Networks, 114 J.Am.Chem.Soc. 6700 (1992), describe gels made from hydrolysis and condensation of monomers such as benzene with two ethoxysilyl groups; the gels were dried and the macroporous polymer network

collapsed yielding a microporous polysilsesquioxane xerogel.

SUMMARY OF THE INVENTION

The present invention provides porous hybrid organic-silica integrated circuit dielectrics. It has been discovered that porous silica has problems including brittleness and cracking; and this can limit available processing steps. Further, carbon-carbon, carbon-hydrogen, and carbon-fluorine bonds typically are less polarizable than the silicon-oxygen bonds of silica, so porous hybrid dielectrics have a lower permittivity than comparably porous silica.

The porous hybrid-organic-silica has advantages over porous silica including lower permittivity for a given xerogel density and increased material flexibility to limit brittleness problems during integrated circuit fabrication.

BRIEF DESCRIPTION OF THE DRAWINGS

Figure 1 shows a chemical reaction illustrating hydrolyzation of an alkoxide in a solvent;

Figure 2 shows a chemical reaction illustrating the condensation of a hydrolyzed alkoxide;

Figure 3 shows a cross-sectional elevation view of a first preferred embodiment intermetal level dielectric in accordance with the present invention;

Figure 4 shows a chemical reaction for a dielectric which hydrolyzes in a solution of ethylene glycol, ethanol water and 1M HNO₃;

Figure 5 shows a chemical reaction illustrating the elimination of hydroxyls;

Figure 6 shows a chemical reaction for a condensation process which further polymerizes oligomers;

Figures 7a-c show a cross-sectional elevation view of a preferred embodiment method of fabrication;

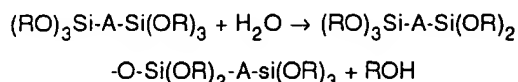
Figures 8a-b show monomers for bridging groups for use with the present invention; and

Figures 9a-e shows alternative preferred embodiment dielectric structures.

DESCRIPTION OF THE PREFERRED EMBODIMENTS

Porous hybrid organic-silica dielectrics derive from monomers of the general form (RO)₃Si-A-Si(OR)₃ where R is any convenient alkyl group and A represents

an organic bridging group; this contrasts with the prior art monomer $\text{Si}(\text{OR})_4$. For example, A could be methylene, phenylene, biphenylene, xylylene, and so forth as illustrated in the preferred embodiments. Hydrolysis and condensation of the monomers provide gels analogous to the prior art:



A lack of polarizable bonds in A helps lower the permittivity and fluoro substitutions provide further preferred embodiments with the additional advantage of higher temperature tolerance due to the stability of carbon-fluorine bonds.

Figure 3 shows a cross sectional view of a preferred embodiment intermetal level dielectrics (IMDs) of xerogel 110 plus silicon dioxide 120 and a reaction barrier (passivation layer 106. Metal lines 104 have widths of about 0.25-0.5 microns, a height of about 0.7 microns, and minimal spacing also of about 0.25 microns. Pre-metal level dielectric (PMD) covers the transistor.

A first preferred embodiment dielectric has monomer 1,4-bis(triethoxysilyl)-benzene which hydrolyzes in a solution of ethylene glycol, ethanol, water, and 1M HNO_3 by refluxing for 1-2 hours at 70°C (molar ratios of 1:3:1.5:1.5:0.042 of monomer, ethylene glycol, ethanol, water, and nitric acid) by the reactions illustrated in Figure 4.

The mild acidic conditions catalyze the hydrolysis, and higher temperatures (e.g., 70°C) increase the reaction rate, but ethanol boils at about 78°C. Replacements of two or more ethoxy groups per monomer may occur; however, the competing condensation of the hydroxyl groups to form Si-O-Si bonded dimers, trimers, ... eliminates hydroxyls by reactions as illustrated in Figure 5.

The hydrolysis plus condensation reactions slowly convert the monomers to oligomers of varying sizes, and the viscosity of the solution increases. Upon reaching a suitable degree of polymerization, the solution is cooled down to room temperature and diluted with ethanol (up to 300%) which yields a shelf life of several months or longer. Typically, the average oligomer will be made of 3-10 monomers and have most of its ethoxy groups replaced by hydroxyl groups or siloxane bonds. The oligomers may crosslink during condensation due to the large number of hydroxyl sites on each oligomer.

A base such as ammonium hydroxide (NH_4OH) catalyzes the further condensation of the oligomers; 0.25M NH_4OH (10% by volume) can be added to the oligomer solution just prior to spin coating. Alternatively, the oligomer solution can be used without the base addition. A 200mm (or 8 inch) diameter wafer requires about 3 ml of solution to provide a coating of about 1 micron average thickness. A spin speed of 1000-5000 rpm for about 10-15 seconds typically suffices. Various spin speeds can be programmed in the spin coating process to con-

trol film streaks, and backside rinse and edge bead removal also can be incorporated to remove edge and backside deposits. Spray or dip coating may also be used. The condensation reaction further polymerizes the oligomers and thereby forms a solvent-saturated thin film gel with a silsesquioxane polymer network roughly illustrated in Figure 6.

After coating, the thin film gel is aged to continue condensation and network formation. The solvent is maintained in the gel by a saturated atmosphere of ethylene glycol over the wafer. An aging temperature of 120°C for 2-4 minutes completes the condensation; a base catalyst may be introduced into the atmosphere. A lower temperature ageing would demand a greater ageing time.

Solvent evaporation during ageing can cause premature drying and substantial shrinkage of the gel, which increases the film density and permittivity and induces film cracking. Thus, solvent evaporation is limited by controlling the atmosphere over the wafer or by the use of less volatile solvents such as glycerol in place of ethanol.

The overall hydrolysis/condensation converts roughly 70% of the original ethoxysilicon R-O-Si bonds into siloxane Si-O-Si bonds and the remaining ethoxysilicon bonds into mostly silanol Si-O-H bonds. The surface Si-O-H groups are active and hydrophilic, but are isolated on the network and do not further condense.

The network has micropores with diameters less than 10 nm. Note the 250 nm minimal spacing between adjacent metal lines in Figure 3 greatly exceeds pore size and the metal line geometry has little impact on gel formation.

After ageing, the wafer is rinsed with ethanol on a spinner to replace the high-surface-tension solvent ethylene glycol in the pores to reduce the capillary pressure during subsequent drying. Due to the small pore size (small radius of curvature), high capillary pressure exists during solvent evaporation (i.e., when a pore surface is partially wetted so the liquid surface tension is asymmetrical) and can cause the polymer network to collapse, producing a denser film.

Further, the pore surface Si-O-H groups present a hydrophilic surface which can adsorb moisture; this will increase the film permittivity and corrode adjacent metal surfaces. Also, possible further condensation reactions of the SiOH groups during drying can cause permanent shrinkage of the network. Therefore, the wafer is rinsed with hexamethyldisilazane (HMDS) (CH_3)₃Si-NH-Si(CH_3)₃ to modify the pore surfaces by replacing the Si-O-H groups with Si-O-Si(CH_3)₃ groups which are hydrophobic and also cannot further condense.

Next, the wafer is rinsed with heptane or hexane to further lower capillary pressure during gel drying. Lastly, the gel is dried by placing the wafer on a hot plate, for example at 300-350°C for about 60 seconds. This leaves a xerogel (the polymer network) with air filled pores.

The HMDS or other surface modification could also be performed after drying if the polymer network is strong enough to withstand the capillary pressure during drying.

The following section describes use of the foregoing xerogel method in fabrication of one of the IMD layers of Figure 3.

Figures 7a-c illustrate fabrication steps for a preferred embodiment xerogel IMD structure which also contains a passivation (reaction barrier) layer for the xerogel. In particular, Figure 7a shows clad aluminum lines 204 of widths 0.25-0.6 microns, heights 0.7 microns, and minimal spacings between lines 0.25 microns. Conformal passivation layer 206 on metal lines 204 and underlying dielectric provides a chemical reaction barrier for metal lines 204, protecting them from corrosion. Passivation layer 206 may be silicon dioxide, and has a thickness of 10-50 nm for example, and may be deposited by (plasma enhanced) CVD.

Figure 7b shows oligomer solution spun on to form thin film gel 208. This uses the previously described oligomer solution and spin on with condensation catalyst. An average film 208 thickness of 0.3-0.5 microns fills in the minimal spacings despite their depths of 0.7 microns; the film thickness over metal lines 204 is only about 0.1 microns.

The gel is processed as previously described (age, replace solvent, modify pore surface, and dry) to form xerogel 210. Then overlying silicon oxide 220 is deposited and planarized, such as by chemical mechanical polishing (CMP), to yield a planar surface as shown in Figure 7c. Via formation and filling yields the lower IMD layer as in Figure 3.

The spin on to form gel 208 provides a reasonably planar surface, so the CMP of the overlying silicon oxide may be omitted.

The monomer for a first preferred embodiment can be prepared by first adding a small crystal of iodine to a mixture of 15 g of magnesium turnings and 450 ml of TEOS in 300 ml of tetrahydrofuran (THF) and refluxing the mixture under a nitrogen atmosphere. Next, a solution of 48 g of 1,4-dibromobenzene in 100 ml of THF is added dropwise to the refluxing mixture over a period of approximately 2 hours. Within 30 minutes of initiating the addition the reaction becomes mildly exothermic. The reaction mixture is kept refluxing for a period of 1 hour after the completion of the addition of the dibromide. The gray-green mixture is cooled to room temperature, and then the THF is removed in vacuo. Hexane is added to precipitate any remaining magnesium salts in solution and filter the mixture under nitrogen to yield a clear, light brown solution. The hexane is removed in vacuo, and the remaining TEOS is distilled off in vacuo to leave a brown oil. The brown oil is distilled (130-135°C at 200 mTorr) to give a clear colorless oil monomer.

A second embodiment xerogel IMD is a fluorinated version of the first preferred embodiment. In particular, the xerogel has fluorine substituted for the hydrogen on

the benzene ring bridging group. All four hydrogens, or only some, may be fluorine substituted; the greater the fluorine content, the better the temperature tolerance and the lower the permittivity when all other parameters remain fixed.

The fluorinated xerogel may be made from a fluorinated monomer with the same processing steps or may be fluorinated after xerogel fabrication by exposure to F_2 at low pressure. The fluorination after fabrication should swell the xerogel due to the larger size of a fluorine atom as compared to hydrogen, but the swelling should only decrease porosity. The fluorination also evolves HF which must be pumped away to avoid metal or oxide etching for the case of fluorination after anisotropic etching. Also, the surface modification with HMDS to replace silanol groups may be replaced with a fluorinated version $(CF_3)_3Si-NH-Si(CF_3)_3$.

Integrated circuit fabrication usually includes very high temperature initial processing steps, but after metal line formation, typically aluminum based, processing temperatures peak at about 450°C (the sintering temperature for aluminum) due to the low melting point of aluminum. Consequently, IMD materials should be thermally stable up to roughly 500°C in an inert atmosphere. The conjugated bond stability of the preceding bridging group examples provides such thermal stability for the xerogels; indeed, the use of pore surface modification with phenyl groups in place of methyl groups enhances thermal stability. That is, replace the pore surface groups $-O-Si(CH_3)_3$ with $-O-Si(C_6H_5)_3$ groups.

Similarly, (partial) fluorination typically increases thermal stability, so (partially) fluorinated version of the preceding such as $(RO)_3Si-C_6F_4-Si(OR)_3$ monomers or surface modification groups such as $-O-Si(CF_3)_3$ or $-O-Si(C_6F_5)_3$ enhance thermal stability.

Further preferred embodiments are similar to the first preferred embodiment but use different bridging groups in the monomer and xerogel. In particular, the bridging groups may consist of alkanes, branched alkanes, alkenes, branched alkenes, alkynes, branched alkynes, cycloalkanes, and arenes as exemplified by the following monomers illustrated in Figures 8a-b.

The alkane, alkene, and alkyne chains may have from 1 to 12 carbon atoms; with more than 12 carbon atoms the polymer network begins to resemble polyethylene. Similarly, alkene and alkyne chains of similar length provide somewhat similar xerogels. Cycloalkanes with 3 to 8 carbon rings may be used. Fused or linked benzene or other rings may be used provided the shortest path of carbon atoms between silicon atoms does not exceed 12.

The selection of bridging group depends upon the desired xerogel thermal stability and flexibility. In particular, thermal stability increases from alkane to comparable alkene to comparable alkyne to comparable cycloalkane to comparable arene. Conversely, flexibility increases in reverse order: arenes being the least flexible and the alkane being the most flexible.

With all of these bridging groups, fluorination increases thermal stability. A drawback of fluorination is possible metal corrosion from the fluorine.

Also, copolymers of two or more of the foregoing monomers could be used to have intermediate characteristics.

The preferred embodiment xerogels may be used in alternative preferred embodiment IMD structures as heuristically illustrated in cross sectional views by Figures 9a-f. In particular, Figure 9a shows a xerogel with overlying oxide and vias over the metal lines; this is the same as Figure 7c plus vias and with the passivation layer omitted.

Figure 9b shows a xerogel in a minimal spacing between metal lines and on the open field away from the minimal spacing. This xerogel structure derives from an etchback down to the metal lines of the original spun on xerogel as illustrated in Figure 7b. An overlying oxide would be deposited on the etched back xerogel to complete the IMD. The etched back xerogel has the advantage of preserving the xerogel in the minimal spacing but reducing the thickness in the open field and thus reducing the mechanical strength demands. It also prevents xerogel blowout during via etch. Indeed, the more conformal the original spun on xerogel, the thinner the etched back xerogel in the open field while maintaining the xerogel filled minimal spacing.

Figure 9c shows oxide masks on the metal lines and xerogel only in the minimal spacing; subsequent deposition of oxide and planarization completes the IMD layer. The structure of Figure 9c can conveniently be fabricated by first using the oxide masks for the metal etch to form the metal lines shown, next spin on xerogel which fills the minimal spacing plus the open field and covers the oxide masks, and then etch back to clear the open field but leaving the minimal spacing filled at least to the height of the metal lines. This differs from the etchback of Figure 9b in that the oxide masks essentially extend the minimal spacing vertically so the etchback can remove the open field xerogel before removing xerogel between the metal lines. For example, if the metal lines are 0.7 microns high, the oxide mask 0.3 microns high, and xerogel thickness 0.5 microns over the open field and 0.2 microns over the oxide masks, then an etchback of 0.5 microns will just clear the open field but leave 0.7 microns in the minimal spacing. Of course, xerogel left on the exterior sidewall of the metal lines would not be detrimental; either isotropic or anisotropic etchback works.

Figure 9d has xerogel only in an etched slot between minimally-spaced metal lines, this allows the xerogel to extend above and below (by slot etching into underlying dielectric) the metal lines and thereby also presents low permittivity material to fringing electric fields. Fabrication of this IMD structure proceeds by the steps of depositing a metal followed by the deposition of an oxide, masking and etching the oxide and the metal depositing a passivation layer, spinning on and drying

xerogel which will fill the minimal spacings plus cover the oxide, and lastly etching back to remove the xerogel from top of the oxide leaving it only in the slots.

Figure 9e shows a damascene structure using xerogel. In particular, the xerogel is first formed (prior to the metal lines), then trenches are anisotropically etched trenches (plus possible vias to underlying conductors) in the xerogel, then a blanket deposit of metal fills the trenches and covers the xerogel, and lastly CMP to remove the metal on the upper xerogel surface but leaves the metal in the trenches to form metal lines.

Figure 9f shows a very thick xerogel which provides the entire IMD (except for possible passivation layers).

The structures of Figures 9a-b,e-f require mechanical strength from the xerogel, especially the structure of Figures 9e-f. In contrast, the structures of Figures 9c-d only use the xerogel in minimal spacings. The mechanical strength depends upon the xerogel density. In a preferred embodiment hybrid xerogels have a lower permittivity than comparable density silica xerogels; thus for a required permittivity, the hybrid xerogels may be denser and thereby stronger than silica xerogels.

The foregoing xerogels between metal (or other conductive) lines can be applied to various integrated circuit types. For example, memories (DRAMs, SRAMs, flash EPROMs, et cetera) have many sets of long parallel conductive lines such as bitlines, wordlines, straps, address and data busses, and so forth, and the xerogel filling minimal spacings in such steps of parallel lines decreases capacitive coupling and associated crosstalk.

The preferred embodiments may be varied in many ways while retaining one or more of the features of organic bridging groups in silica xerogels used as integrated circuit dielectrics. For example, the xerogels could be used as dielectrics in various locations within integrated circuits such as between polysilicon or polycide gates and wordlines and about microwave circuit elements.

The dimensions of the preferred embodiment structures could be varied, such as the minimal spacing between conductive lines being 0.18 or 0.13 microns or less, the metal line height could vary and the metal be copper or tungsten or alloys or silicides such as TiSi_2 or CoSi_2 or nitrides such as TiN or WN , and the oxide dielectric could be fluorinated oxide (SiO_xF_y) or an oxynitride or a multilayer stack of these, the passivation layer could be omitted or silicon nitride or oxynitride used, and so forth.

Claims

1. An integrated circuit dielectric, comprising:
a xerogel filling at least a portion of a space between a first and a second conductor, said xerogel including a polymer network including organic bridging groups.

2. The dielectric of Claim 1, wherein:

wherein said bridging groups are selected from a group materials comprising: of alkanes, alkenes, alkynes, arenes, and cycloalkanes, with the shortest path of carbon atoms across the bridging group being at most 12. 5

10

15

20

25

30

35

40

45

50

55

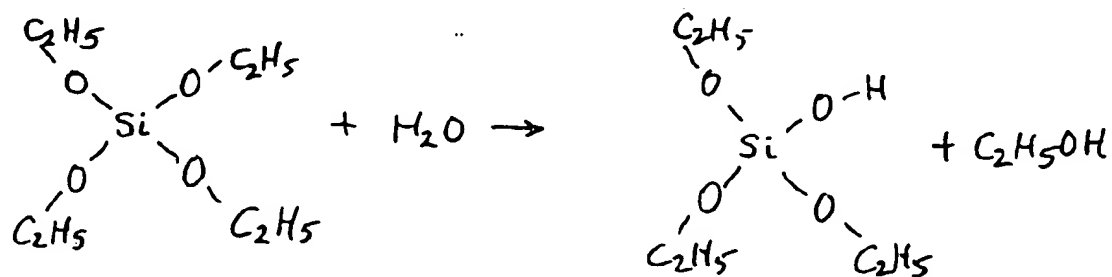


Figure 1.

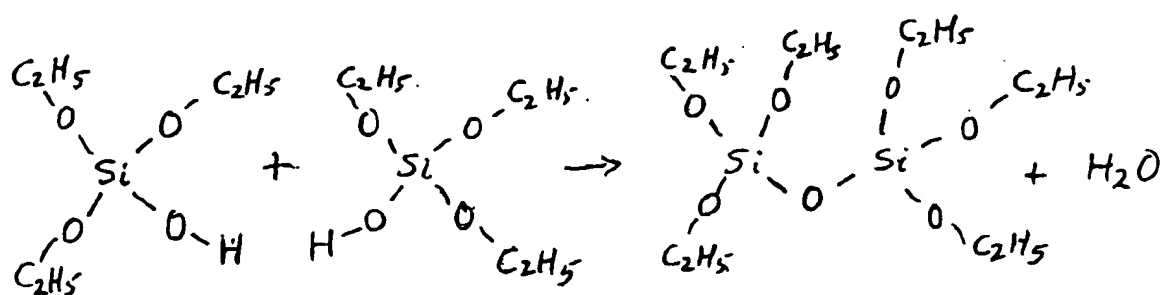


Figure 2.

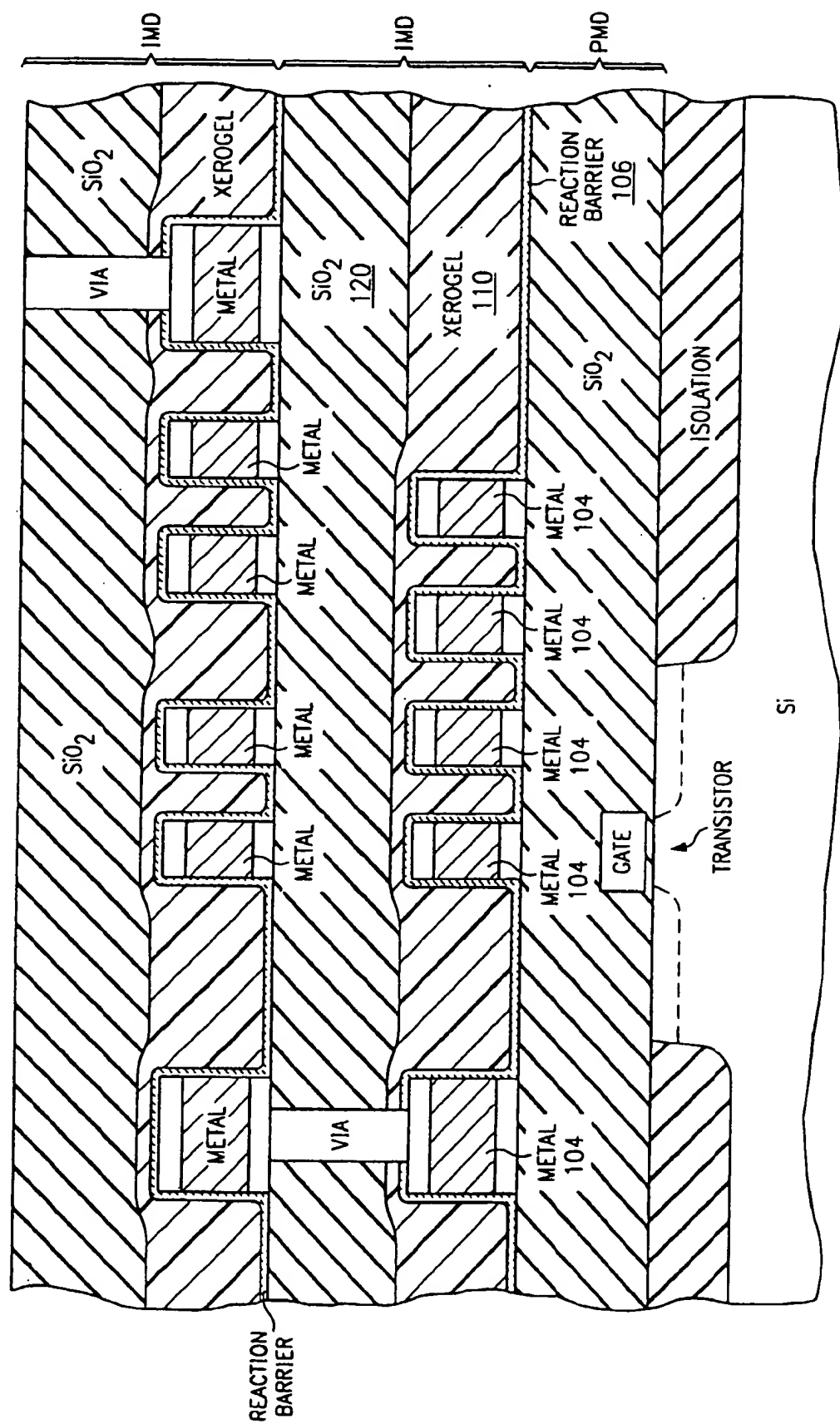


Figure 3.

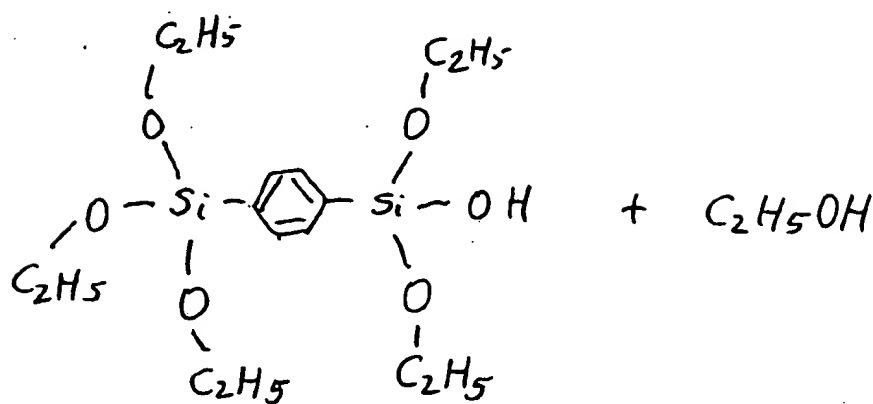
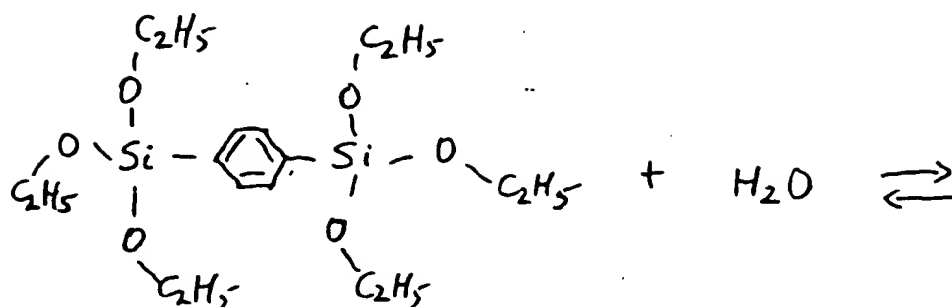


Figure 4.

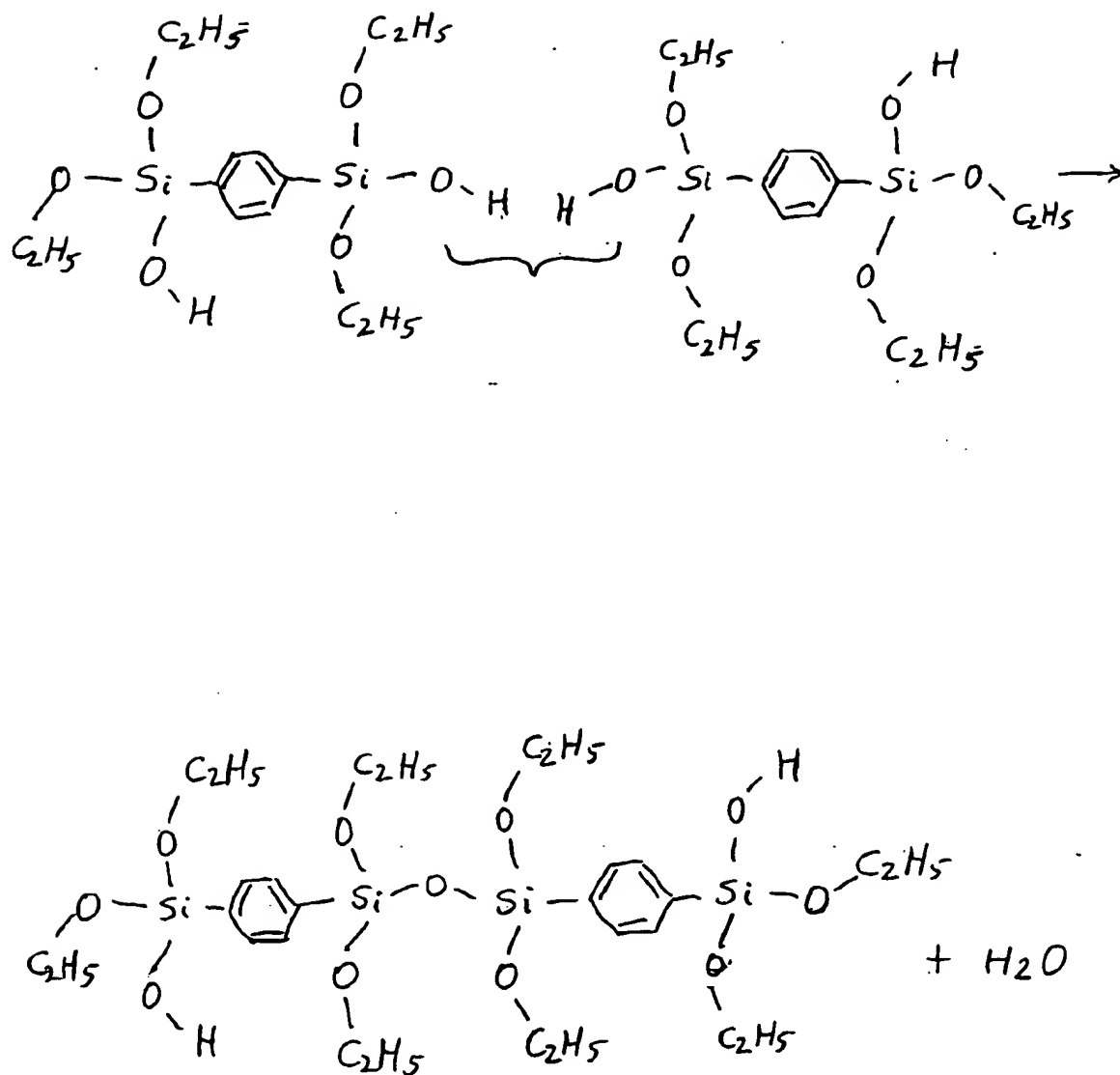


Figure 5.

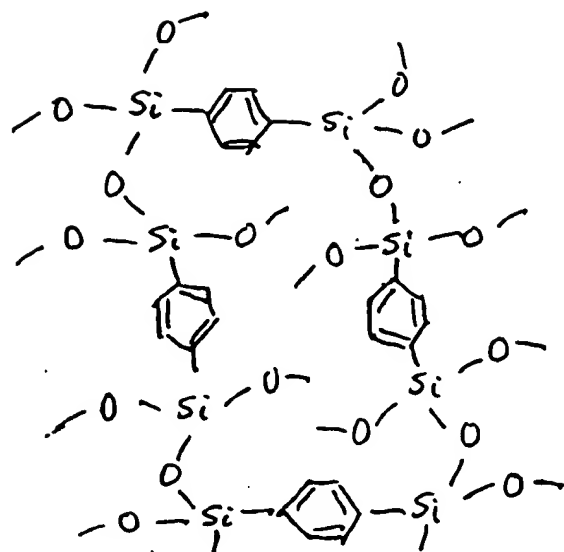


Figure 6.

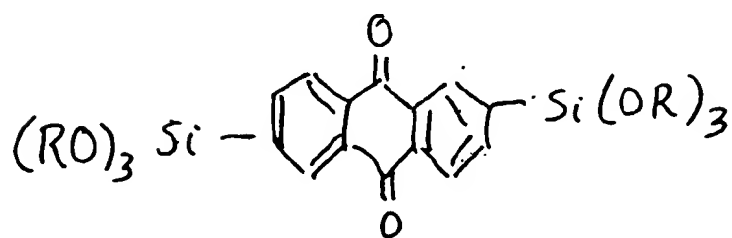
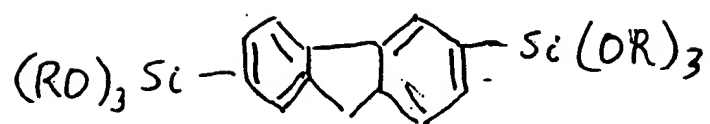


Figure 8b.

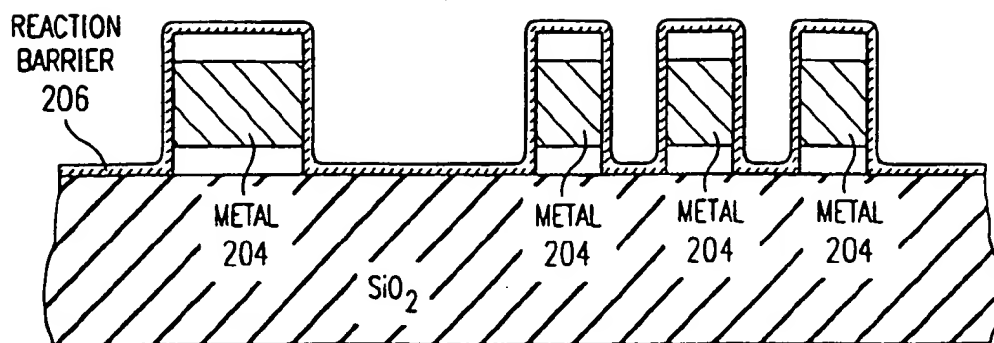


Figure 7a.

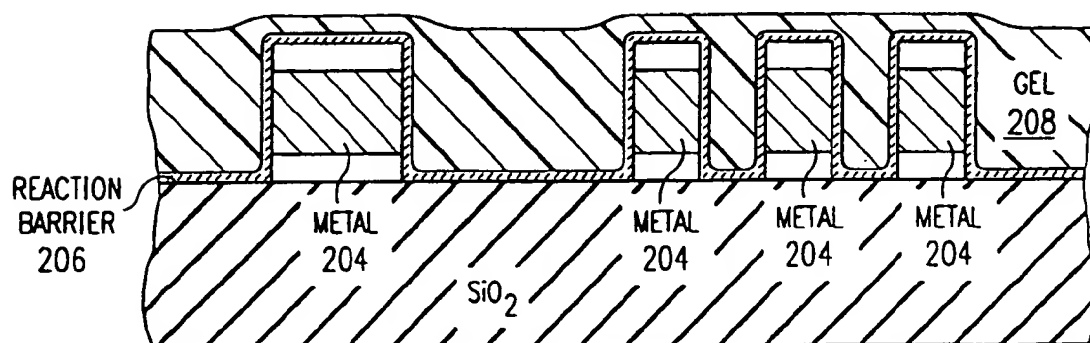


Figure 7b.

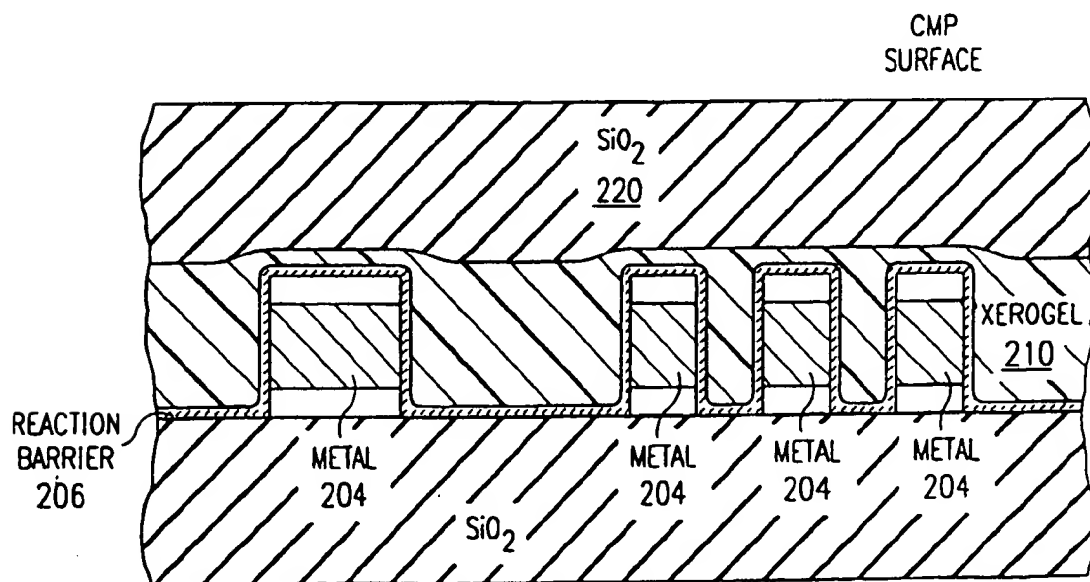


Figure 7c.

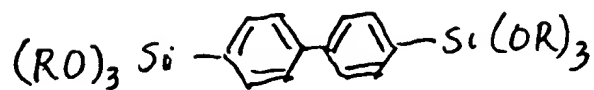
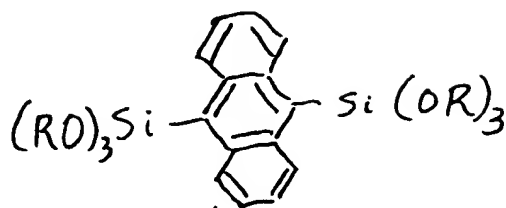
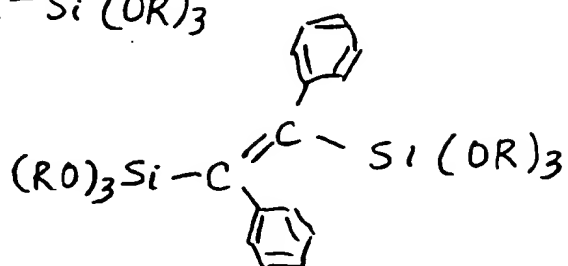
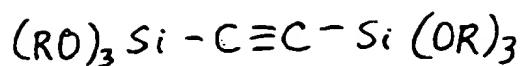
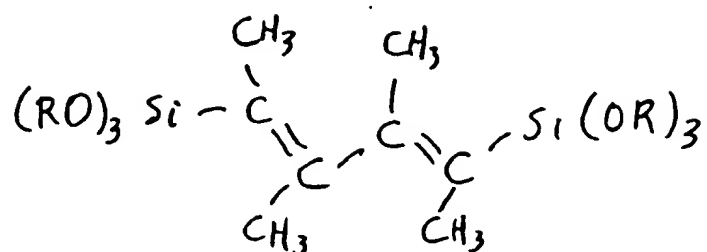
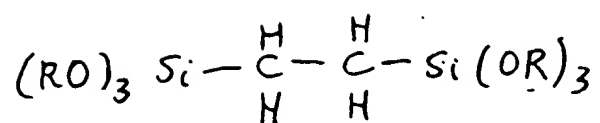


Figure 8a.

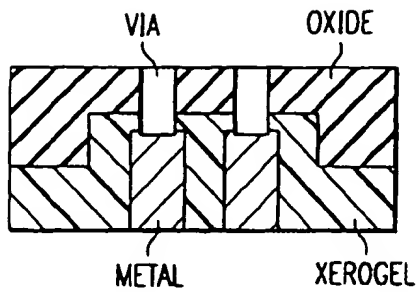


Figure 9a.

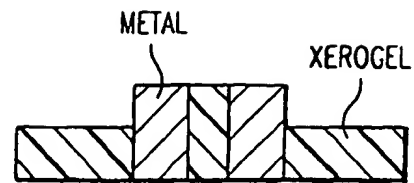


Figure 9b.

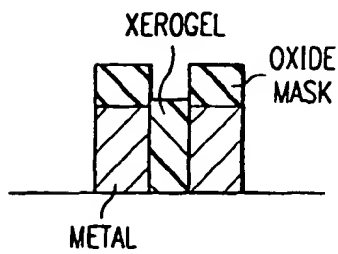


Figure 9c.

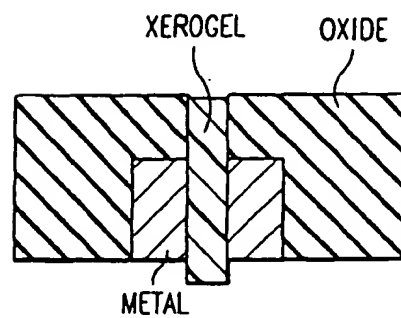


Figure 9d.

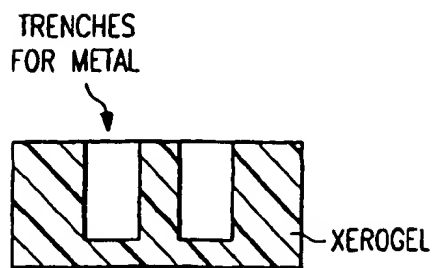


Figure 9e.

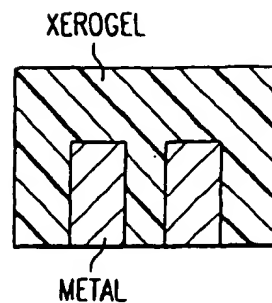


Figure 9f.